

GAS INLET APPARATUS FOR PROCESS CHAMBER, SEMICONDUCTOR EQUIPMENT, MOUNTING METHOD, AND DISMOUNTING METHOD

ABSTRACT

The present disclosure provides a gas inlet apparatus for a process chamber, a semiconductor equipment, a mounting method, and a dismounting method, relates to the field of semiconductor processing technology, and aims to solve a problem of poor uniformity of a process gas when entering a process chamber in the existing technology. The gas inlet apparatus for the process chamber applied to a semiconductor equipment includes: a showerhead cover plate (110), which is provided with first gas through holes (111); and a flow guide assembly, a first shower cavity (110b) being formed by a space between the flow guide assembly and the showerhead cover plate (110) and communicated with the first gas through holes (111), and second gas through holes (310) being formed in a sidewall of the first shower cavity (110b) and configured to communicate the first shower cavity (110b) with the process chamber; and the flow guide assembly including a temperature control plate (200), which is located below the showerhead cover plate (110) and is arranged opposite to the first gas through holes (111). The gas inlet apparatus for the process chamber can improve the uniformity of the process gas when entering the process chamber.

FIGURE 1